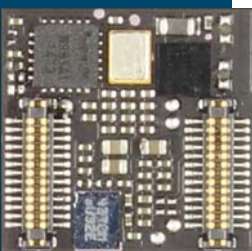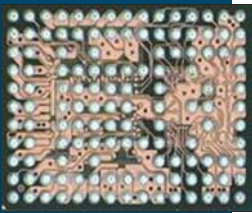# SiP for Mobile and Wearable Applications:
Market Forecasts and the Changing Business Model

With the proliferation of mobile electronic products and the ongoing push for greater functionality in a smaller area, miniaturization has become a key word for system-in-package (SiP). SiP is defined as two or more dissimilar die, typically combined with other components such as passives, filters, MEMS, sensors or antennas, assembled into a standard package format to create a functional system or subsystem. SiPs are found in smartphones, tablets, wearable electronics (including medical products), and other consumer products. High-performance gaming systems, computers, and network systems also use SiP, as do automotive electronics and future connectivity products. Drivers differ depending on the application and include form factor, need for highly integrated solutions, low-power requirements, shielding, and cost.

This report examines products using SiP and the constructions found in today's applications. Potential changes to business models are addressed. The 76-page report with full references provides forecasts for the SiP market in units by application and package type. Key requirements for SiP are examined and the roles of design, EMI shielding, and known good die are discussed. Assembly service providers are listed.

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